



Welcome to [E-XFL.COM](https://www.e-xfl.com)

Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

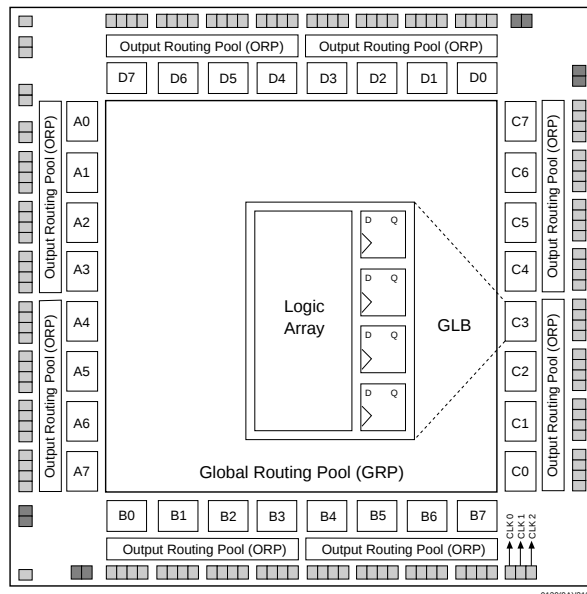
Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	32
Number of Macrocells	128
Number of Gates	6000
Number of I/O	128
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	176-LQFP
Supplier Device Package	176-TQFP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/isplsi-2128e-180lt176

Features

- **SUPERFAST HIGH DENSITY IN-SYSTEM PROGRAMMABLE LOGIC**
 - 6000 PLD Gates
 - 128 I/O Pins, Eight Dedicated Inputs
 - 128 Registers
 - High Speed Global Interconnect
 - Wide Input Gating for Fast Counters, State Machines, Address Decoders, etc.
 - Small Logic Block Size for Random Logic
 - 100% Functional/JEDEC Upward Compatible with ispLSI 2128 Devices
- **HIGH PERFORMANCE E²CMOS[®] TECHNOLOGY**
 - $f_{max} = 180$ MHz Maximum Operating Frequency
 - $t_{pd} = 5.0$ ns Propagation Delay
 - TTL Compatible Inputs and Outputs
 - 5V Programmable Logic Core
 - ispJTAG[™] In-System Programmable via IEEE 1149.1 (JTAG) Test Access Port
 - User-Selectable 3.3V or 5V I/O Supports Mixed-Voltage Systems
 - PCI Compatible Outputs
 - Open-Drain Output Option
 - Electrically Erasable and Reprogrammable
 - Non-Volatile
 - Unused Product Term Shutdown Saves Power
- **ispLSI OFFERS THE FOLLOWING ADDED FEATURES**
 - Increased Manufacturing Yields, Reduced Time-to-Market and Improved Product Quality
 - Reprogram Soldered Devices for Faster Prototyping
- **OFFERS THE EASE OF USE AND FAST SYSTEM SPEED OF PLDs WITH THE DENSITY AND FLEXIBILITY OF FIELD PROGRAMMABLE GATE ARRAYS**
 - Complete Programmable Device Can Combine Glue Logic and Structured Designs
 - Enhanced Pin Locking Capability
 - Three Dedicated Clock Input Pins
 - Synchronous and Asynchronous Clocks
 - Programmable Output Slew Rate Control to Minimize Switching Noise
 - Flexible Pin Placement
 - Optimized Global Routing Pool Provides Global Interconnectivity

Functional Block Diagram



Description

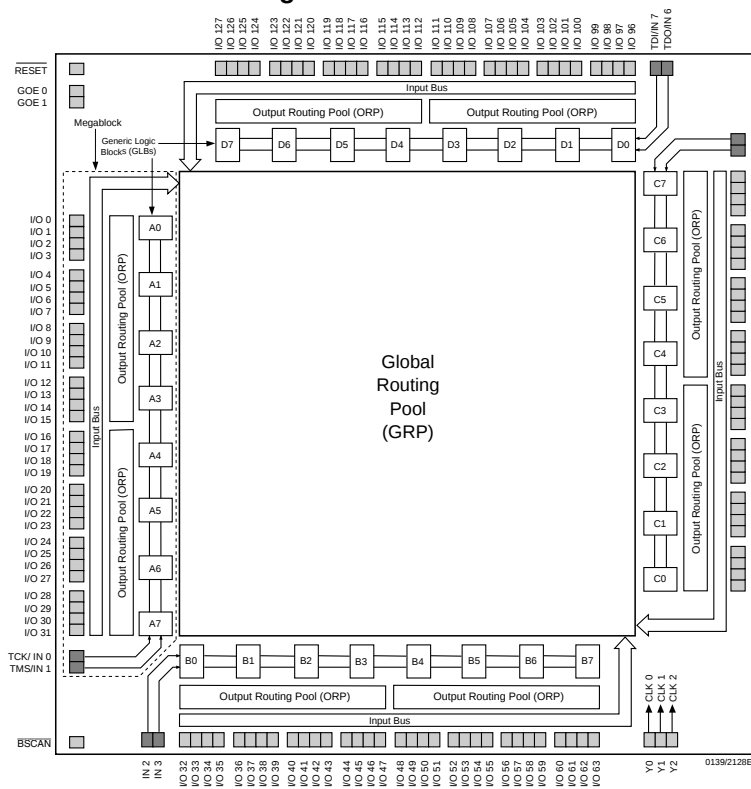
The ispLSI 2128E is a High Density Programmable Logic Device. The device contains 128 Registers, 128 Universal I/O pins, eight Dedicated Input pins, three Dedicated Clock Input pins, two dedicated Global OE input pins and a Global Routing Pool (GRP). The GRP provides complete interconnectivity between all of these elements. The ispLSI 2128E features 5V in-system programmability and in-system diagnostic capabilities. The ispLSI 2128E offers non-volatile reprogrammability of all logic, as well as the interconnect to provide truly reconfigurable systems.

The basic unit of logic on the ispLSI 2128E device is the Generic Logic Block (GLB). The GLBs are labeled A0, A1 .. D7 (see Figure 1). There are a total of 32 GLBs in the ispLSI 2128E device. Each GLB is made up of four macrocells. Each GLB has 18 inputs, a programmable AND/OR/Exclusive OR array, and four outputs which can be configured to be either combinatorial or registered. Inputs to the GLB come from the GRP and dedicated inputs. All of the GLB outputs are brought back into the GRP so that they can be connected to the inputs of any GLB on the device.

The device also has 128 I/O cells, each of which is directly connected to an I/O pin. Each I/O cell can be

Functional Block Diagram

Figure 1. ispLSI 2128E Functional Block Diagram



individually programmed to be a combinatorial input, output or bi-directional I/O pin with 3-state control. The signal levels are TTL compatible voltages and the output drivers can source 4 mA or sink 8 mA. Each output can be programmed independently for fast or slow output slew rate to minimize overall output switching noise. By connecting the VCCIO pins to a common 5V or 3.3V power supply, I/O output levels can be matched to 5V or 3.3V compatible voltages. When connected to a 5V supply, the I/O pins provide PCI-compatible output drive.

Eight GLBs, 32 I/O cells, two dedicated inputs and two ORPs are connected together to make a Megablock (see Figure 1). The outputs of the eight GLBs are connected to a set of 32 universal I/O cells by the two ORPs. Each ispLSI 2128E device contains four Megablocks.

The GRP has as its inputs, the outputs from all of the GLBs and all of the inputs from the bi-directional I/O cells. All of these signals are made available to the inputs of the GLBs. Delays through the GRP have been equalized to minimize timing skew.

Clocks in the ispLSI 2128E device are selected using the dedicated clock pins. Three dedicated clock pins (Y0, Y1, Y2) or an asynchronous clock can be selected on a GLB basis. The asynchronous or Product Term clock can be generated in any GLB for its own clock.

Programmable Open-Drain Outputs

In addition to the standard output configuration, the outputs of the ispLSI 2128E are individually programmable, either as a standard totem-pole output or an open-drain output. The totem-pole output drives the specified V_{oh} and V_{ol} levels, whereas the open-drain output drives only the specified V_{ol} . The V_{oh} level on the open-drain output depends on the external loading and pull-up. This output configuration is controlled by a programmable fuse. The default configuration when the device is in bulk erased state is totem-pole configuration. The open-drain/totem-pole option is selectable through the Lattice software tools.

Absolute Maximum Ratings ¹

Supply Voltage V_{CC} -0.5 to +7.0V
 Input Voltage Applied -2.5 to $V_{CC} + 1.0V$
 Off-State Output Voltage Applied -2.5 to $V_{CC} + 1.0V$
 Storage Temperature -65 to 150°C
 Case Temp. with Power Applied -55 to 125°C
 Max. Junction Temp. (T_J) with Power Applied ... 150°C

1. Stresses above those listed under the "Absolute Maximum Ratings" may cause permanent damage to the device. Functional operation of the device at these or at any other conditions above those indicated in the operational sections of this specification is not implied (while programming, follow the programming specifications).

DC Recommended Operating Condition

SYMBOL	PARAMETER	MIN.	MAX.	UNITS
V_{CC}	Supply Voltage: Logic Core, Input Buffers $T_A = 0^\circ C$ to $+70^\circ C$	4.75	5.25	V
V_{CCIO}	Supply Voltage: Output Drivers 5V	4.75	5.25	V
	3.3V	3.0	3.6	V
V_{IL}	Input Low Voltage	0	0.8	V
V_{IH}	Input High Voltage	2.0	$V_{CC} + 1$	V

Table 2-0005/2128E

Capacitance ($T_A = 25^\circ C$, $f = 1.0$ MHz)

SYMBOL	PARAMETER	TYP	UNITS	TEST CONDITIONS
C_1	Dedicated Input Capacitance	8	pf	$V_{CC} = 5.0V$, $V_{IN} = 2.0V$
C_2	I/O Capacitance	8	pf	$V_{CC} = 5.0V$, $V_{IO} = 2.0V$
C_3	Clock Capacitance	10	pf	$V_{CC} = 5.0V$, $V_Y = 2.0V$

Table 2-0006/2128E

Erase/Reprogram Specification

PARAMETER	MINIMUM	MAXIMUM	UNITS
Erase/Reprogram Cycles	10,000	—	Cycles

Table 2-0008/2128E

Switching Test Conditions

Input Pulse Levels	GND to 3.0V
Input Rise and Fall Time 10% to 90%	1.5 ns
Input Timing Reference Levels	1.5V
Output Timing Reference Levels	1.5V
Output Load	See Figure 2

3-state levels are measured 0.5V from steady-state active level.

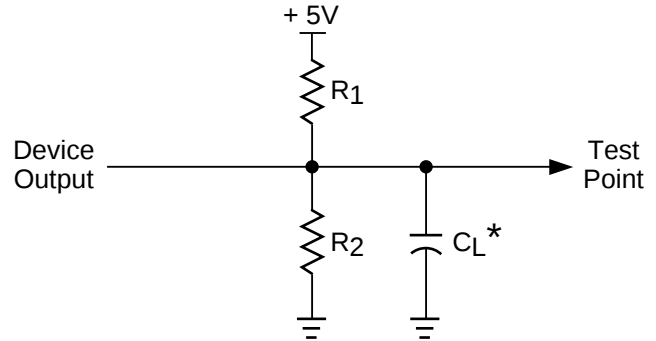
Table 2-0003/2128E

Output Load Conditions (see Figure 2)

TEST CONDITION		R1	R2	CL
A		470Ω	390Ω	35pF
B	Active High	∞	390Ω	35pF
	Active Low	470Ω	390Ω	35pF
C	Active High to Z at $V_{OH} - 0.5V$	∞	390Ω	5pF
	Active Low to Z at $V_{OL} + 0.5V$	470Ω	390Ω	5pF

Table 2 - 0004A/2000

Figure 2. Test Load



* C_L includes Test Fixture and Probe Capacitance.

0213A

DC Electrical Characteristics

Over Recommended Operating Conditions

SYMBOL	PARAMETER	CONDITION	MIN.	TYP. ³	MAX.	UNITS
V_{OL}	Output Low Voltage	$I_{OL} = 8 \text{ mA}$	—	—	0.4	V
V_{OH}	Output High Voltage	$I_{OH} = -4 \text{ mA}$	2.4	—	—	V
I_{IL}	Input or I/O Low Leakage Current	$0V \leq V_{IN} \leq V_{IL} (\text{Max.})$	—	—	-10	μA
I_{IH}	Input or I/O High Leakage Current	$(V_{CCIO} - 0.2)V \leq V_{IN} \leq V_{CCIO}$	—	—	10	μA
		$V_{CCIO} \leq V_{IN} \leq 5.25V$	—	—	10	μA
I_{IL-PU}	I/O Active Pull-Up Current	$0V \leq V_{IN} \leq 2.0V$	-10	—	-250	μA
I_{OS}^1	Output Short Circuit Current	$V_{CCIO} = 5.0V \text{ or } 3.3V, V_{OUT} = 0.5V$	—	—	-240	mA
$I_{CC}^{3,4}$	Operating Power Supply Current	$V_{IL} = 0.0V, V_{IH} = 3.0V$ $f_{TOGGLE} = 1 \text{ MHz}$	—	165	—	mA

Table 2-0007/2128E

- One output at a time for a maximum duration of one second. $V_{OUT} = 0.5V$ was selected to avoid test problems by tester ground degradation. Characterized but not 100% tested.
- Measured using eight 16-bit counters.
- Typical values are at $V_{CC} = 5V$ and $T_A = 25^\circ C$.
- Unused inputs held at 0.0V.
- Maximum I_{CC} varies widely with specific device configuration and operating frequency. Refer to the Power Consumption section of this data sheet and the Thermal Management section of the Lattice Semiconductor Data Book or CD-ROM to estimate maximum I_{CC} .

External Timing Parameters

Over Recommended Operating Conditions

PARAMETER	TEST COND. ⁴	# ²	DESCRIPTION ¹	-180		-135		-100		UNITS
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
t_{pd1}	A	1	Data Prop Delay, 4PT Bypass, ORP Bypass	–	5.0	–	7.5	–	10.0	ns
t_{pd2}	A	2	Data Prop Delay	–	7.5	–	10.0	–	13.0	ns
f_{max}	A	3	Clk Freq with Internal Feedback ³	180	–	135	–	100	–	MHz
f_{max} (Ext.)	–	4	Clk Freq with External Feedback ($\frac{1}{t_{su2} + t_{co1}}$)	125	–	100	–	77.0	–	MHz
f_{max} (Tog.)	–	5	Clk Frequency, Max. Toggle	200	–	143	–	100	–	MHz
t_{su1}	–	6	GLB Reg Setup Time before Clk, 4 PT Bypass	4.0	–	5.0	–	6.5	–	ns
t_{co1}	A	7	GLB Reg Clk to Output Delay, ORP Bypass	–	3.0	–	4.0	–	5.0	ns
t_{h1}	–	8	GLB Reg Hold Time after Clk, 4 PT Bypass	0.0	–	0.0	–	0.0	–	ns
t_{su2}	–	9	GLB Reg Setup Time before Clk	5.0	–	6.0	–	8.0	–	ns
t_{co2}	–	10	GLB Reg Clk to Output Delay	–	3.5	–	4.5	–	6.0	ns
t_{h2}	–	11	GLB Reg Hold Time after Clk	0.0	–	0.0	–	0.0	–	ns
t_{r1}	A	12	External Reset Pin to Output Delay	–	7.0	–	10.0	–	13.5	ns
t_{rw1}	–	13	External Reset Pulse Duration	4.0	–	5.0	–	6.5	–	ns
t_{p_{to}een}	B	14	Input to Output Enable	–	10.0	–	12.0	–	15.0	ns
t_{p_{to}edis}	C	15	Input to Output Disable	–	10.0	–	12.0	–	15.0	ns
t_{goeen}	B	16	Global OE Output Enable	–	5.0	–	7.0	–	9.0	ns
t_{goedis}	C	17	Global OE Output Disable	–	5.0	–	7.0	–	9.0	ns
t_{wh}	–	18	External Synch Clk Pulse Duration, High	2.5	–	3.5	–	5.0	–	ns
t_{wl}	–	19	External Synch Clk Pulse Duration, Low	2.5	–	3.5	–	5.0	–	ns

Table 2-0030A/2128E

1. Unless noted otherwise, all parameters use a GRP load of four GLBs, 20 PTXOR path, ORP and Y0 clock.
2. Refer to Timing Model in this data sheet for further details.
3. Standard 16-bit counter using GRP feedback.
4. Reference Switching Test Conditions section.

Internal Timing Parameters¹

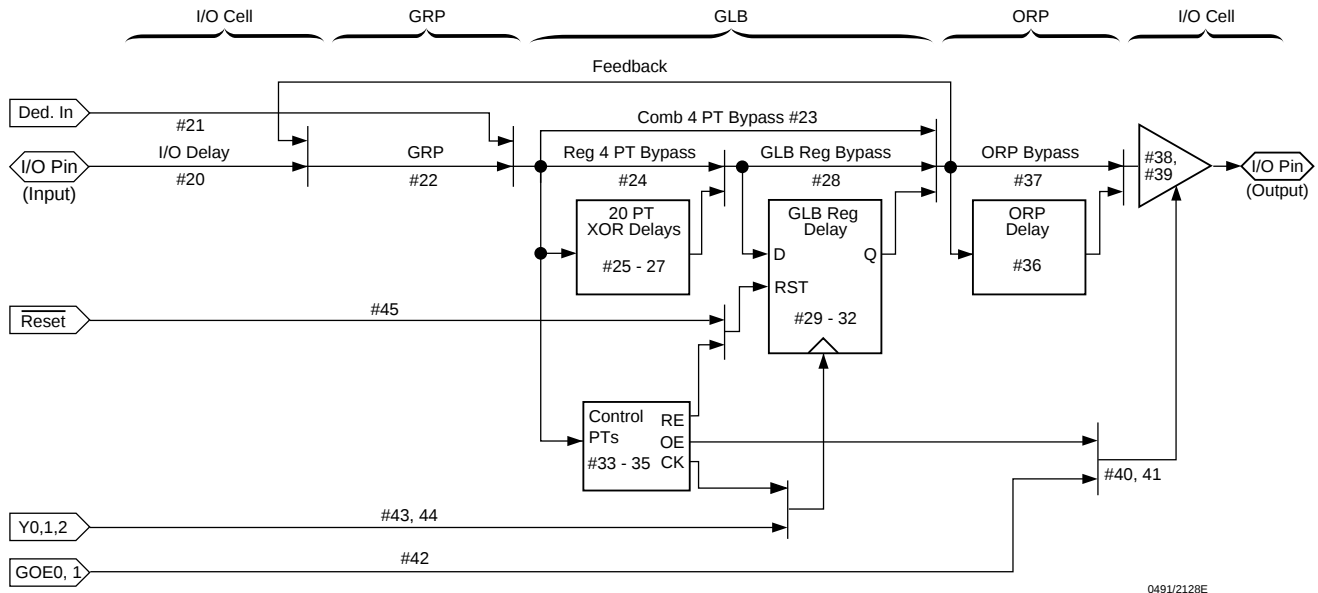
Over Recommended Operating Conditions

PARAMETER	# ²	DESCRIPTION	-180		-135		-100		UNITS
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Inputs									
tio	20	Input Buffer Delay	–	0.5	–	0.5	–	0.5	ns
tdin	21	Dedicated Input Delay	–	1.1	–	1.7	–	2.2	ns
GRP									
tgrp	22	GRP Delay	–	0.6	–	1.2	–	1.7	ns
GLB									
t4ptbpc	23	4 Product Term Bypass Path Delay (Combinatorial)	–	1.9	–	3.7	–	5.8	ns
t4ptbpr	24	4 Product Term Bypass Path Delay (Registered)	–	2.9	–	4.2	–	5.8	ns
t1ptxor	25	1 Product Term/XOR Path Delay	–	3.9	–	5.2	–	6.8	ns
t20ptxor	26	20 Product Term/XOR Path Delay	–	3.9	–	5.2	–	7.3	ns
txoradj	27	XOR Adjacent Path Delay ³	–	3.9	–	5.2	–	8.0	ns
tgbp	28	GLB Register Bypass Delay	–	0.0	–	0.5	–	0.5	ns
tgsu	29	GLB Register Setup Time before Clock	0.7	–	0.7	–	1.2	–	ns
tgh	30	GLB Register Hold Time after Clock	3.3	–	4.3	–	4.0	–	ns
tgco	31	GLB Register Clock to Output Delay	–	0.3	–	0.3	–	0.3	ns
tgro	32	GLB Register Reset to Output Delay	–	0.6	–	1.1	–	1.3	ns
tptre	33	GLB Product Term Reset to Register Delay	–	4.8	–	6.0	–	6.1	ns
tp toe	34	GLB Product Term Output Enable to I/O Cell Delay	–	5.9	–	6.9	–	8.6	ns
tp tck	35	GLB Product Term Clock Delay	1.0	4.0	2.5	5.5	4.1	7.1	ns
ORP									
torp	36	ORP Delay	–	0.9	–	1.0	–	1.4	ns
torpbp	37	ORP Bypass Delay	–	0.4	–	0.5	–	0.4	ns
Outputs									
tob	38	Output Buffer Delay	–	1.6	–	1.6	–	1.6	ns
tsl	39	Output Slew Limited Delay Adder	–	1.5	–	1.5	–	10.0	ns
toen	40	I/O Cell OE to Output Enabled	–	3.0	–	3.4	–	4.2	ns
todis	41	I/O Cell OE to Output Disabled	–	3.0	–	3.4	–	4.2	ns
tgoe	42	Global Output Enable	–	2.0	–	3.6	–	4.8	ns
Clocks									
tgy0	43	Clock Delay, Y0 to Global GLB Clock Line (Ref. clock)	0.7	0.7	1.6	1.6	2.7	2.7	ns
tgy1/2	44	Clock Delay, Y1 or Y2 to Global GLB Clock Line	0.9	0.9	1.8	1.8	2.7	2.7	ns
Global Reset									
tgr	45	Global Reset to GLB	–	4.4	–	6.3	–	9.2	ns

Table 2-0036A/2128E

1. Internal Timing Parameters are not tested and are for reference only.
2. Refer to Timing Model in this data sheet for further details.
3. The XOR adjacent path can only be used by hard macros.

ispLSI 2128E Timing Model



0491/2128E

Derivations of t_{su} , t_h and t_{co} from the Product Term Clock

$$\begin{aligned}
 t_{su} &= \text{Logic} + \text{Reg } su - \text{Clock (min)} \\
 &= (t_{io} + t_{grp} + t_{20ptxor}) + (t_{gsu}) - (t_{io} + t_{grp} + t_{ptck(min)}) \\
 &= (\#20 + \#22 + \#26) + (\#29) - (\#20 + \#22 + \#35) \\
 3.6 &= (0.5 + 0.6 + 3.9) + (0.7) - (0.5 + 0.6 + 1.0) \\
 t_h &= \text{Clock (max)} + \text{Reg } h - \text{Logic} \\
 &= (t_{io} + t_{grp} + t_{ptck(max)}) + (t_{gh}) - (t_{io} + t_{grp} + t_{20ptxor}) \\
 &= (\#20 + \#22 + \#35) + (\#30) - (\#20 + \#22 + \#26) \\
 3.4 &= (0.5 + 0.6 + 4.0) + (3.3) - (0.5 + 0.6 + 3.9) \\
 t_{co} &= \text{Clock (max)} + \text{Reg } co + \text{Output} \\
 &= (t_{io} + t_{grp} + t_{ptck(max)}) + (t_{gco}) + (t_{orp} + t_{ob}) \\
 &= (\#20 + \#22 + \#35) + (\#31) + (\#36 + \#38) \\
 7.9 &= (0.5 + 0.6 + 4.0) + (0.3) + (0.9 + 0.6)
 \end{aligned}$$

Table 2-0042/2128E

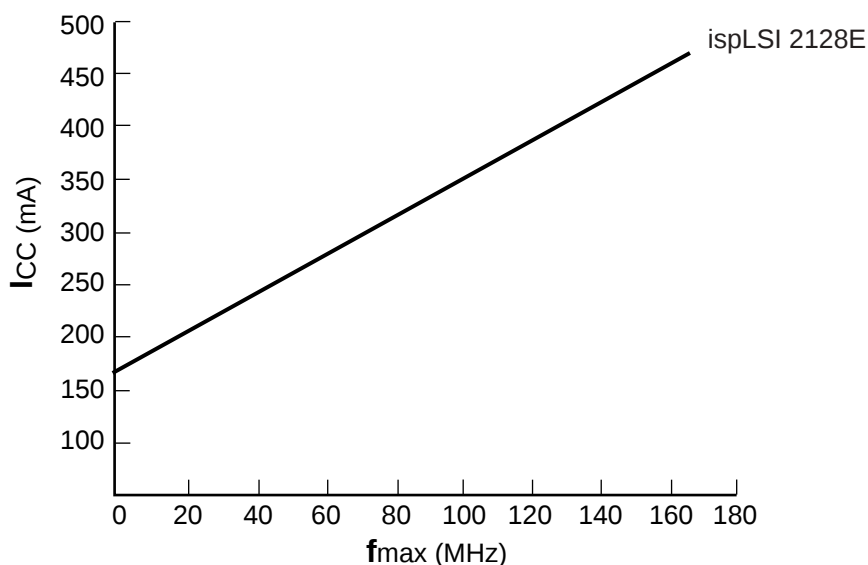
Note: Calculations are based upon timing specifications for the ispLSI 2128E-180L.

Power Consumption

Power consumption in the ispLSI 2128E device depends on two primary factors: the speed at which the device is operating and the number of Product Terms used.

Figure 3 shows the relationship between power and operating speed.

Figure 3. Typical Device Power Consumption vs fmax



Notes: Configuration of eight 16-bit counters
Typical current at 5V, 25° C

I_{CC} can be estimated for the ispLSI 2128E using the following equation:

$$I_{CC} = 27 + (\# \text{ of PTs} * 0.55) + (\# \text{ of nets} * \text{max freq} * 0.0058)$$

Where:

of PTs = Number of Product Terms used in design

of nets = Number of Signals used in device

Max freq = Highest Clock Frequency to the device (in MHz)

The I_{CC} estimate is based on typical conditions (V_{CC} = 5.0V, room temperature) and an assumption of two GLB loads on average exists. These values are for estimates only. Since the value of I_{CC} is sensitive to operating conditions and the program in the device, the actual I_{CC} should be verified.

0127/2128E

Pin Description

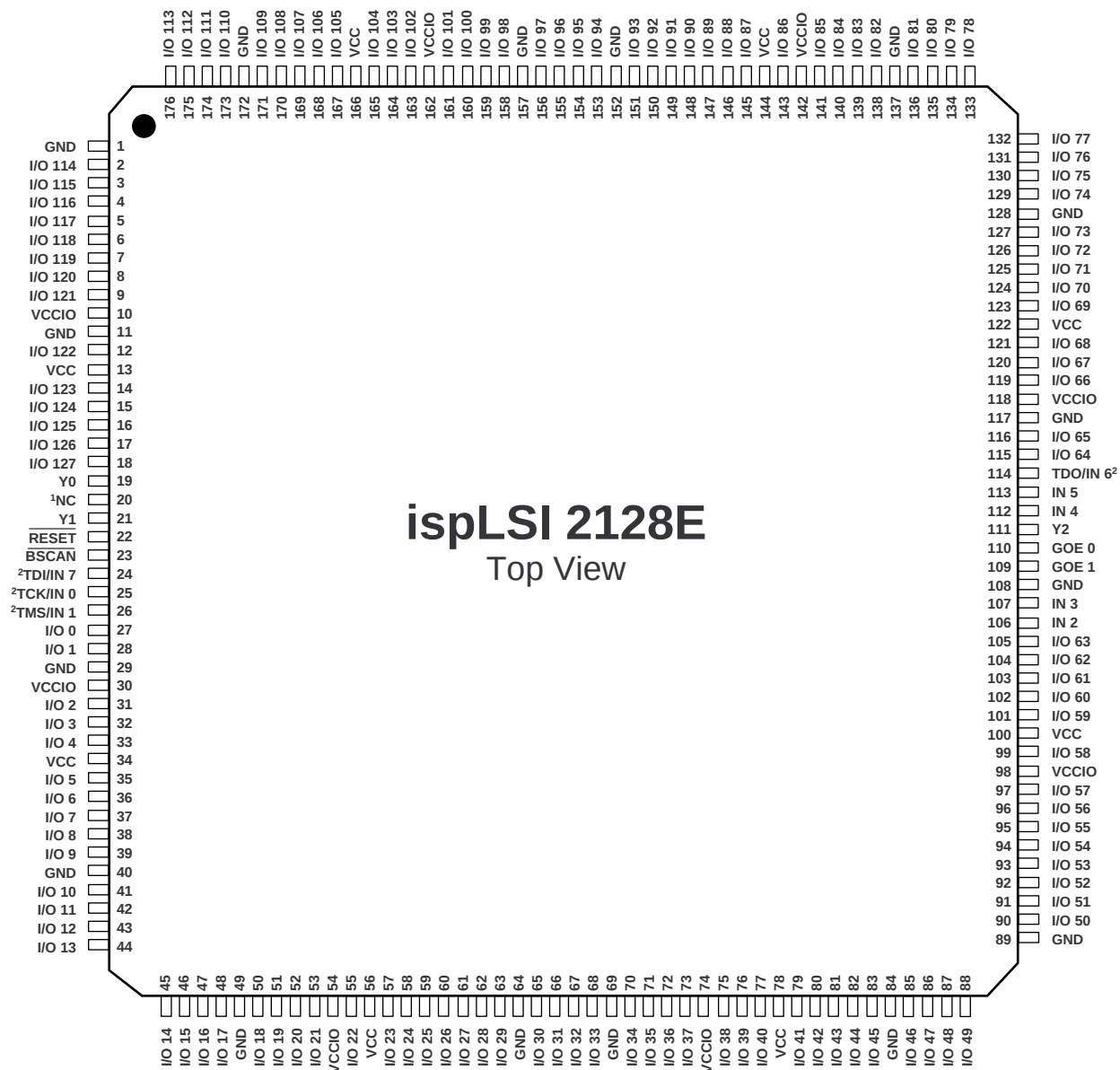
NAME	TQFP PIN NUMBERS	DESCRIPTION
I/O 0 - I/O 4 I/O 5 - I/O 9 I/O 10 - I/O 14 I/O 15 - I/O 19 I/O 20 - I/O 24 I/O 25 - I/O 29 I/O 30 - I/O 34 I/O 35 - I/O 39 I/O 40 - I/O 44 I/O 45 - I/O 49 I/O 50 - I/O 54 I/O 55 - I/O 59 I/O 60 - I/O 64 I/O 65 - I/O 69 I/O 70 - I/O 74 I/O 75 - I/O 79 I/O 80 - I/O 84 I/O 85 - I/O 89 I/O 90 - I/O 94 I/O 95 - I/O 99 I/O 100 - I/O 104 I/O 105 - I/O 109 I/O 110 - I/O 114 I/O 115 - I/O 119 I/O 120 - I/O 124 I/O 125 - I/O 127	27, 28, 31, 32, 33, 35, 36, 37, 38, 39, 41, 42, 43, 44, 45, 46, 47, 48, 50, 51, 52, 53, 55, 57, 58, 59, 60, 61, 62, 63, 65, 66, 67, 68, 70, 71, 72, 73, 75, 76, 77, 79, 80, 81, 82, 83, 85, 86, 87, 88, 90, 91, 92, 93, 94, 95, 96, 97, 99, 101, 102, 103, 104, 105, 115, 116, 119, 120, 121, 123, 124, 125, 126, 127, 129, 130, 131, 132, 133, 134, 135, 136, 138, 139, 140, 141, 143, 145, 146, 147, 148, 149, 150, 151, 153, 154, 155, 156, 158, 159, 160, 161, 163, 164, 165, 167, 168, 169, 170, 171, 173, 174, 175, 176, 2, 3, 4, 5, 6, 7, 8, 9, 12, 14, 15, 16, 17, 18	Input/Output Pins - These are the general purpose I/O pins used by the logic array.
IN 2 - IN 5	106, 107, 112, 113	Dedicated input pins to the device.
GOE 0, GOE 1	110, 109,	Global Output Enable input pins.
$\overline{\text{RESET}}$ Y0, Y1, Y2	22 19, 21, 111	Active Low (0) Reset pin which resets all of the GLB registers in the device. Dedicated Clock inputs. These clock inputs are connected to one of the clock inputs of all the GLBs on the device.
$\overline{\text{BSCAN}}$	23	Input - Dedicated in-system programming enable input pin. This pin is brought low to enable the programming mode. The TMS, TDI, TDO and TCK options become active.
TDI/IN 7 ¹	24	Input - This pin performs two functions. When $\overline{\text{BSCAN}}$ is logic low, it functions as an input pin to load programming data into the device. SDI is also used as one of the two control pins for the ISP state machine. When $\overline{\text{BSCAN}}$ is high, it functions as a dedicated input pin.
TCK/IN 0 ¹	25	Input - This pin performs two functions. When $\overline{\text{BSCAN}}$ is logic low, it functions as a clock pin for the Serial Shift Register. When $\overline{\text{BSCAN}}$ is high, it functions as a dedicated input pin.
TMS/IN 1 ¹	26	Input - This pin performs two functions. When $\overline{\text{BSCAN}}$ is logic low, it functions as pin to control the operation of the programming state machine. When $\overline{\text{BSCAN}}$ is high, it functions as a dedicated input pin.
TDO/IN 6 ¹	114	Output/Input - This pin performs two functions. When $\overline{\text{BSCAN}}$ is logic low, it functions as the pin to read the isp data. When $\overline{\text{BSCAN}}$ is high, it functions as a dedicated input pin.
GND	1, 11, 29, 40, 49, 64, 69, 84, 89, 108, 117, 128, 137, 152, 157, 172	Ground (GND)
VCC	13, 34, 56, 78, 100, 122, 144, 166	V _{CC}
VCCIO	10, 30, 54, 74, 98, 118, 142, 162	Supply voltage for output drivers, 5V or 3.3V. All VCCIO pins must be connected to the same voltage level.
NC	20	No Connect

1. Pins have dual function capability.

Table 2-0002/2128E

Pin Configuration

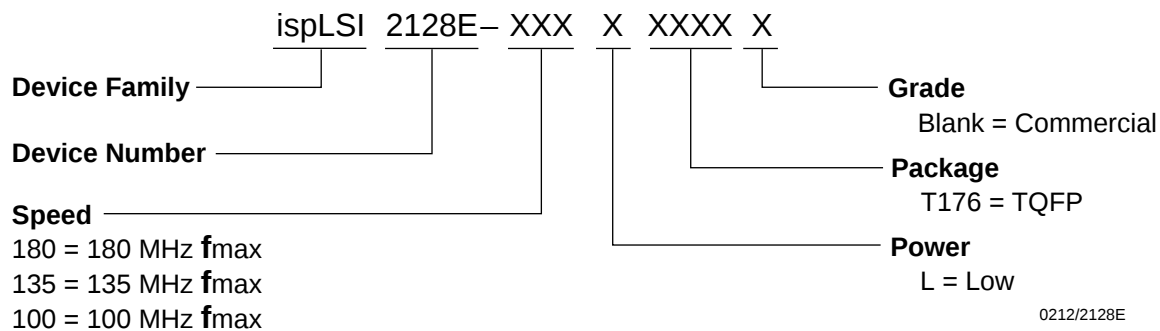
ispLSI 2128E 176-Pin TQFP Pinout Diagram



176-TQFP/2128E

1. NC pins are not to be connected to any active signals, VCC or GND.
2. Pins have dual function capability.

Part Number Description



ispLSI 2128E Ordering Information

FAMILY	f_{max} (MHz)	t_{pd} (ns)	ORDERING NUMBER	PACKAGE
ispLSI	180	5.0	ispLSI 2128E-180LT176	176-Pin TQFP
	135	7.5	ispLSI 2128E-135LT176	176-Pin TQFP
	100	10.0	ispLSI 2128E-100LT176	176-Pin TQFP

Table 2-0041/2128E